TFO-K-SI is an electrically insulating thermally conductive silicone foil for an optimised thermal coupling between electronic packages and heat sinks. Through the specific formulation and filling with thermally conductive ceramic particles a very high thermal conductivity is reached. Under pressure the total thermal resistance is minimised. The fibreglass reinforcement provides for an outstanding mechanic stability and cut-through resistance as well as easy handling. For an easy and reliable pre-assembly the interface material is available with low tack pressure sensitive adhesive on one side.



PROPERTIES

- ☐ Thermal conductivity: 2.5 W/mK
- High thermal contact
- Outstanding mechanic stability through fibreglass reinforcement
- Extraordinary chemical resistance and longterm stability
- ☐ Residue-free removal after use

AVAILABILITY

- Sheet 320 x 1000 mm
- Roll 320 mm x 50 m
- Non tacky
- (TFO-K200-SI)
- Tacky on one side (TFO-K200-SI-A1)
- Die cut parts
- Kiss cut parts on roll
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

- MOSFETs or IGBTs
- Power diodes or AC/DC converters
- □ Power modules

For use in Switch mode power supplies / Motor control units / Automotive engine management systems / UPS units / Solar systems

PROPERTIES	Unit	TF0-K200-SI
Material		Ceramic filled silicone
Colour		Grey
Reinforcement		Fibreglass
Thickness	mm	0.23
Tensile Strength ¹	kpsi	2.9
UL Flammability	UL 94	VO
RoHS Conformity	2002/95/EC	Yes
Thermal		
Resistance ² @ 150 PSI	°C-inch²/W (mm)	0.24
Resistance ² @ 30 PSI	°C-inch²/W (mm)	0.47
Thermal Conductivity	W/mK	2.5
Operating Temperature Range	°C	- 50 to + 200
Electrical		
Breakdown Voltage³	kV AC	2.0
Volume Resistivity	Ohm - cm	2.0 x 10 ¹⁴
Dielectric Constant	@ 1 MHz	4.0

Test Methods: 1 ASTM D 412, 2 ASTM D 5470, 3 ASTM D 149. All data without warranty and subject to change. Please contact us for further data and information

Thickness: 0.23 mm

Rth vs. N/cm² (PSI)

